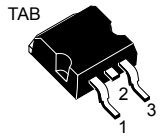
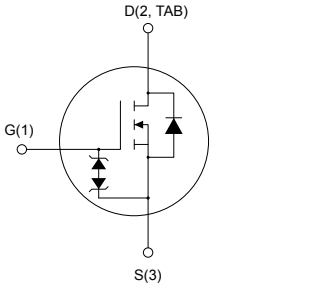
STB30N65DM6AG

Datasheet

Automotive-grade N-channel 650 V, 102 mΩ typ., 28 A MDmesh DM6 Power MOSFET in a D²PAK package



D²PAK



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STB30N65DM6AG	650 V	115 mΩ	28 A

- AEC-Q101 qualified
- Fast-recovery body diode
- Lower $R_{DS(on)}$ per area vs previous generation
- Low gate charge, input capacitance and resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

Applications

- Switching applications

Description

This high-voltage N-channel Power MOSFET is part of the MDmesh DM6 fast-recovery diode series. Compared with the previous MDmesh fast generation, DM6 combines very low recovery charge (Q_{rr}), recovery time (t_{rr}) and excellent improvement in $R_{DS(on)}$ per area with one of the most effective switching behaviors available in the market for the most demanding high-efficiency bridge topologies and ZVS phase-shift converters.

Product status link
STB30N65DM6AG

Product summary	
Order code	STB30N65DM6AG
Marking	30N65DM6
Package	D²PAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±25	V
I_D	Drain current (continuous) at T_C = 25 °C	28	A
I_D	Drain current (continuous) at T_C = 100 °C	18	A
I_{DM}(1)	Drain current (pulsed)	112	A
P_{TOT}	Total power dissipation at T_C = 25 °C	223	W
dv/dt(2)	Peak diode recovery voltage slope	100	V/ns
di/dt(2)	Peak diode recovery current slope	1000	A/µs
dv/dt(3)	MOSFET dv/dt ruggedness	100	V/ns
T_J	Operating junction temperature range	-55 to 150	°C
T_{stg}	Storage temperature range		°C

1. *Pulse width limited by safe operating area.*
2. *I_{SD} ≤ 28 A, V_{DS} (peak) < $V_{(BR)DSS}$, V_{DD} = 400 V.*
3. *V_{DS} ≤ 520 V.*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance, junction-to-case	0.56	°C/W
R_{thJA}(1)	Thermal resistance, junction-to-ambient	30	°C/W

1. *When mounted on a standard 1 inch² area of FR-4 PCB with 2-oz copper.*

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or non-repetitive (pulse width limited by T_J max)	4	A
E_{AS}	Single pulse avalanche energy (starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 100 V)	600	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified.

Table 4. On/off-state

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	650	-	-	V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 650 V	-	-	5	µA
		V_{GS} = 0 V, V_{DS} = 650 V, T_C = 125 °C(1)	-	-	200	µA
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V	-	-	±5	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3.25	4.00	4.75	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 10 A	-	102	115	mΩ

1. *Specified by design, not tested in production.*

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 100 V, f = 1 MHz, V_{GS} = 0 V	-	2000	-	pF
C_{oss}	Output capacitance		-	130	-	pF
C_{rss}	Reverse transfer capacitance		-	1.5	-	pF
$C_{oss\ eq.}$(1)	Equivalent output capacitance	V_{DS} = 0 to 520 V, V_{GS} = 0 V	-	339	-	pF
R_G	Intrinsic gate resistance	f = 1 MHz, open drain	-	1.6	-	Ω
Q_g	Total gate charge	V_{DD} = 520 V, I_D = 28 A, V_{GS} = 0 to 10 V (see Figure 2)	-	46	-	nC
Q_{gs}	Gate-source charge		-	13.5	-	nC
Q_{gd}	Gate-drain charge		-	20	-	nC

1. *$C_{oss\ eq.}$ is defined as the constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.*

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 325 V, I_D = 14 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 1 and Figure 6)	-	17	-	ns
t_r	Rise time		-	3.3	-	ns
$t_{d(off)}$	Turn-off delay time		-	46	-	ns
t_f	Fall time		-	8	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-	-	28	A
I_{SDM}(1)	Source-drain current (pulsed)		-	-	112	A
V_{SD}(2)	Forward on voltage	I_{SD} = 28 A, V_{GS} = 0 V	-	-	1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 28 A, di/dt = 100 A/µs, V_{DD} = 60 V (see Figure 3)	-	126	-	ns
Q_{rr}	Reverse recovery charge		-	0.63	-	µC
I_{RRM}	Reverse recovery current		-	10	-	A
t_{rr}	Reverse recovery time	I_{SD} = 28 A, di/dt = 100 A/µs, V_{DD} = 60 V, T_J = 150 °C (see Figure 3)	-	220	-	ns
Q_{rr}	Reverse recovery charge		-	2.1	-	µC
I_{RRM}	Reverse recovery current		-	19	-	A

1. *Pulse width limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

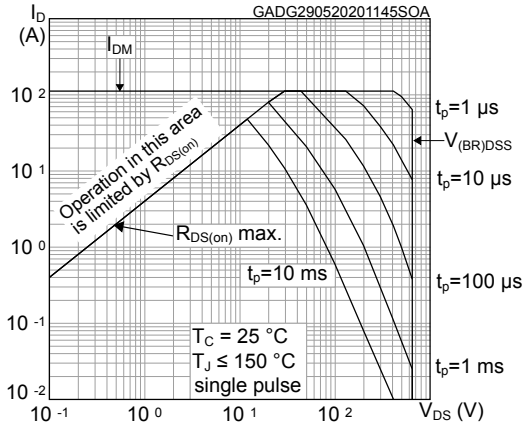


Figure 2. Maximum transient thermal impedance

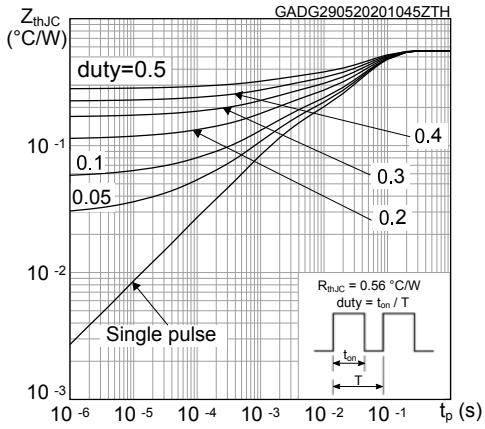


Figure 3. Typical output characteristics

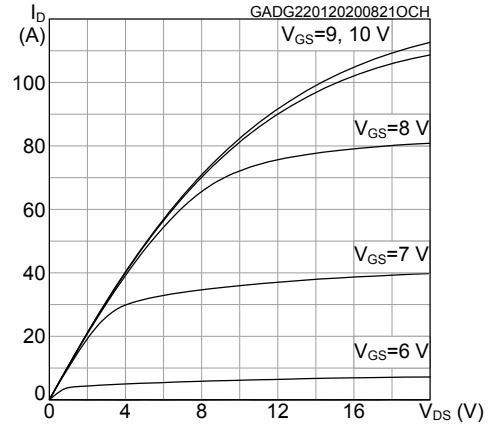


Figure 4. Typical transfer characteristics

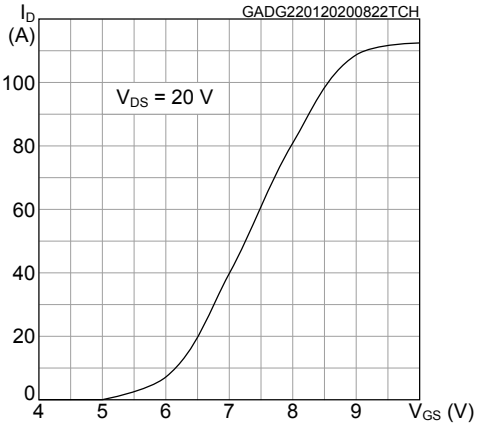


Figure 5. Typical drain-source on-resistance

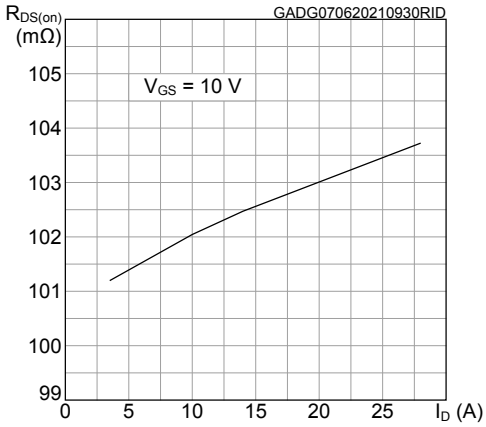


Figure 6. Typical gate charge characteristics

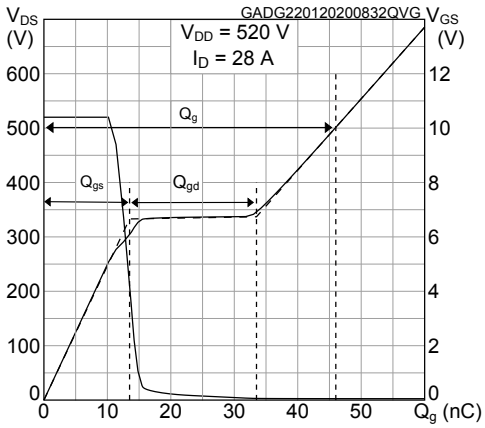


Figure 7. Typical capacitance characteristics

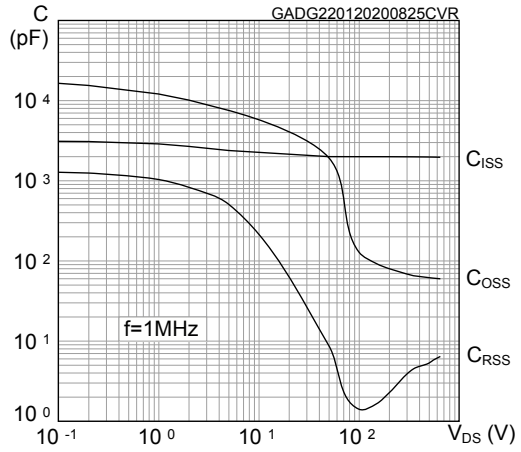


Figure 8. Normalized gate threshold vs temperature

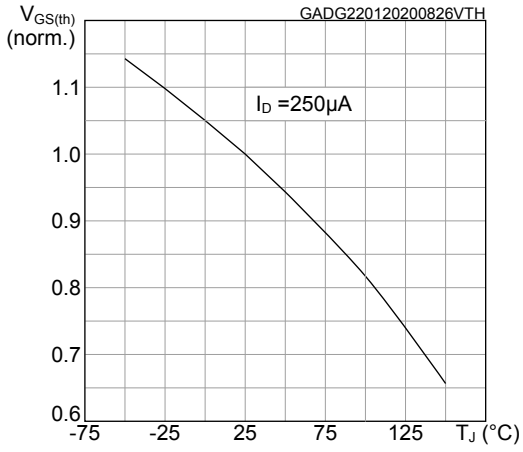


Figure 9. Normalized on-resistance vs temperature

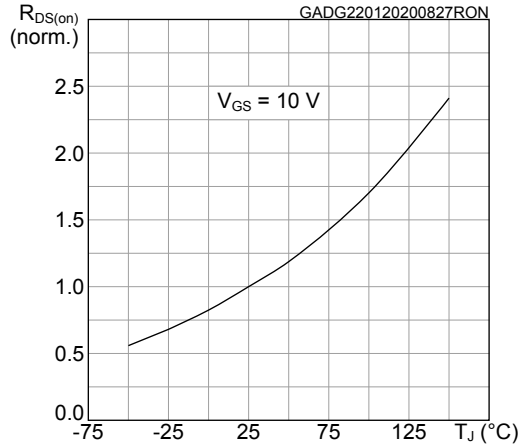


Figure 10. Typical output capacitance stored energy

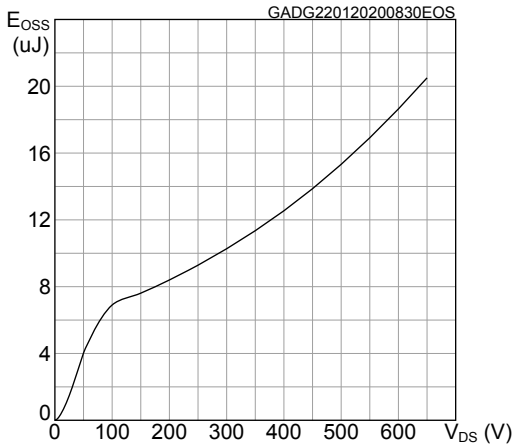


Figure 11. Normalized breakdown voltage vs temperature

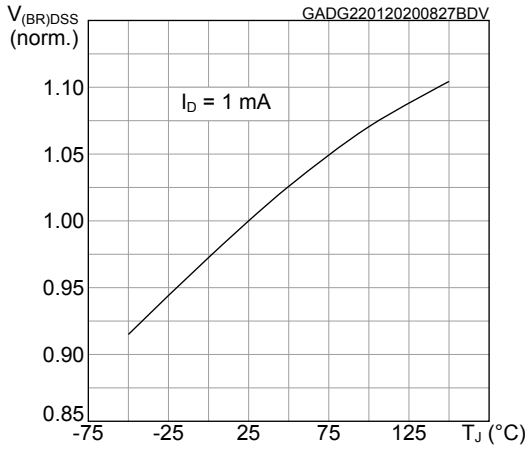
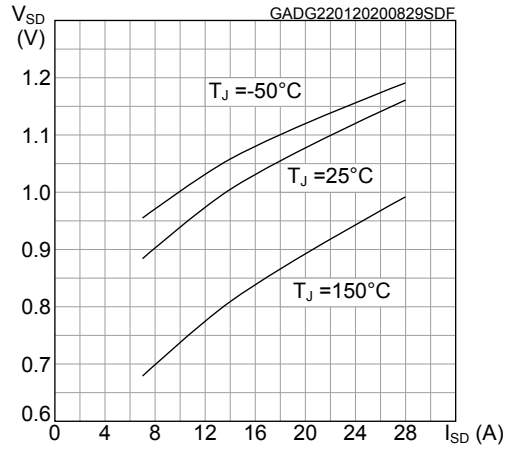
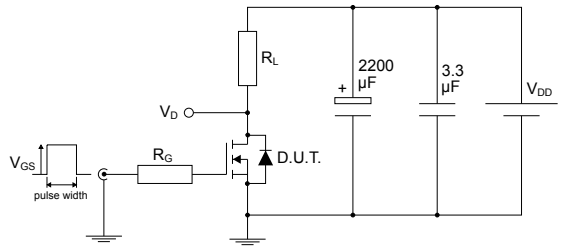


Figure 12. Typical reverse diode forward characteristics



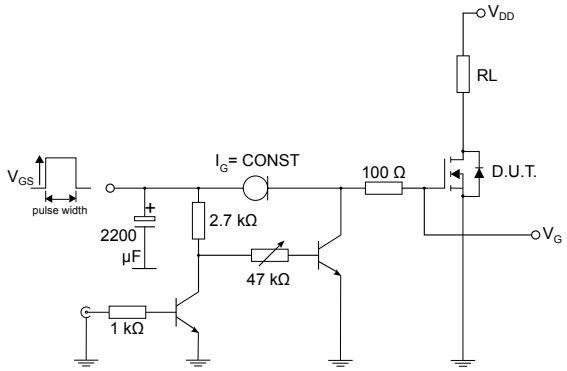
3 Test circuits

Figure 13. Test circuit for resistive load switching times



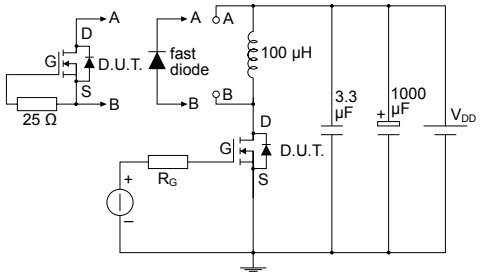
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Figure 14. Test circuit for gate charge behavior



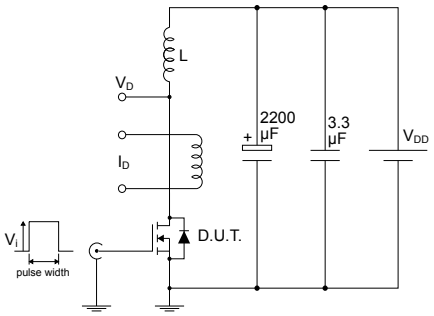
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Figure 15. Test circuit for inductive load switching and diode recovery times



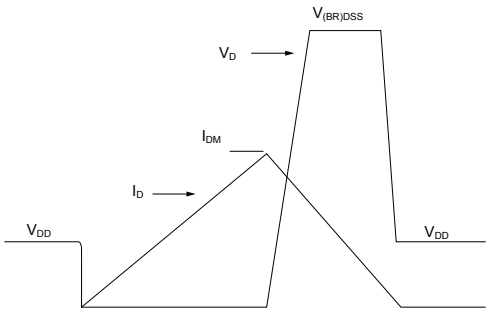
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Figure 16. Unclamped inductive load test circuit



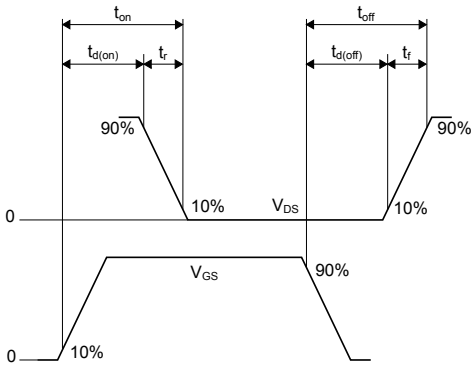
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Figure 17. Unclamped inductive waveform



AM01472v1

Figure 18. Switching time waveform



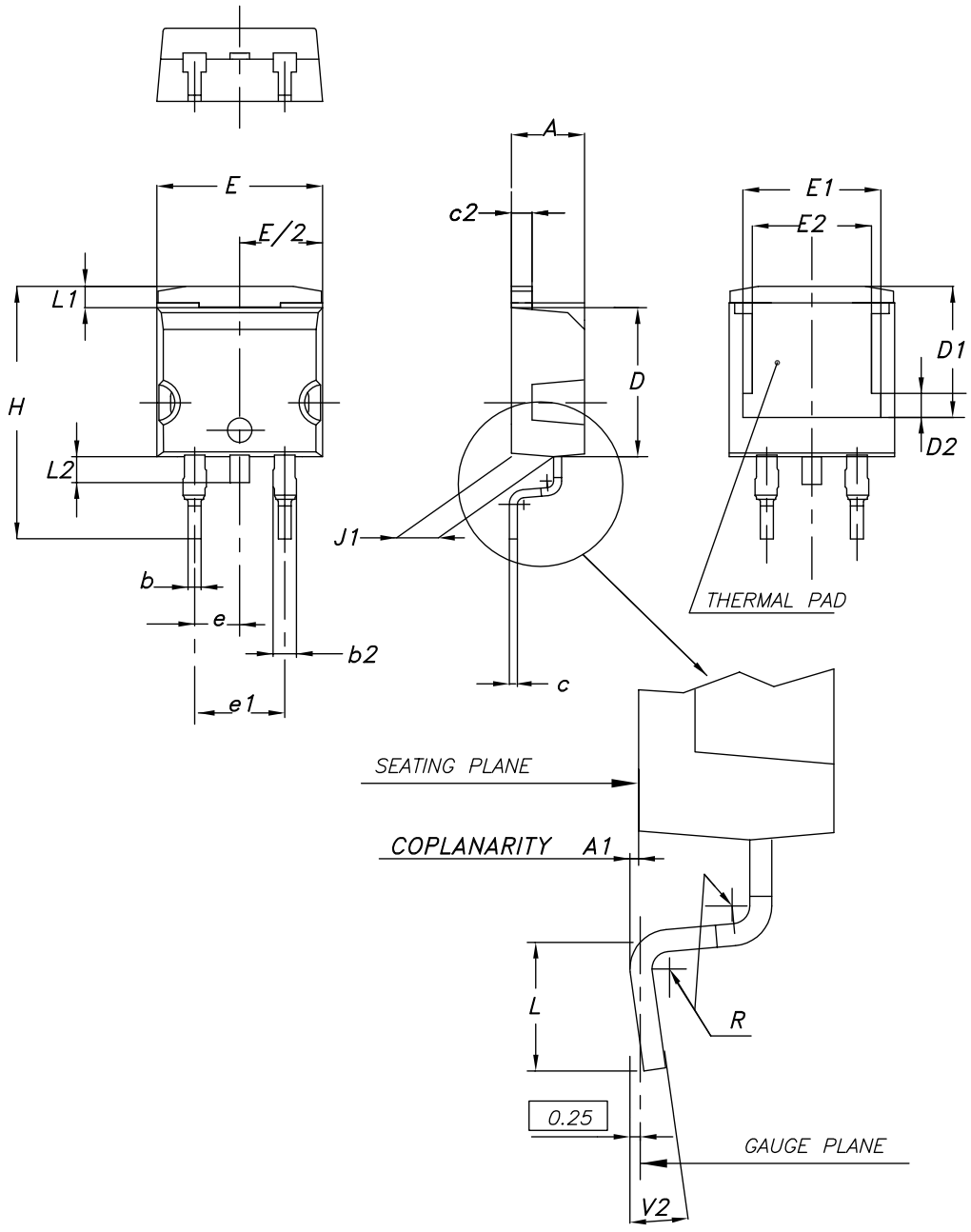
AM01473v1

4 Package information

To meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 D²PAK (TO-263) type A2 package information

Figure 19. **D²PAK (TO-263) type A2 package outline**



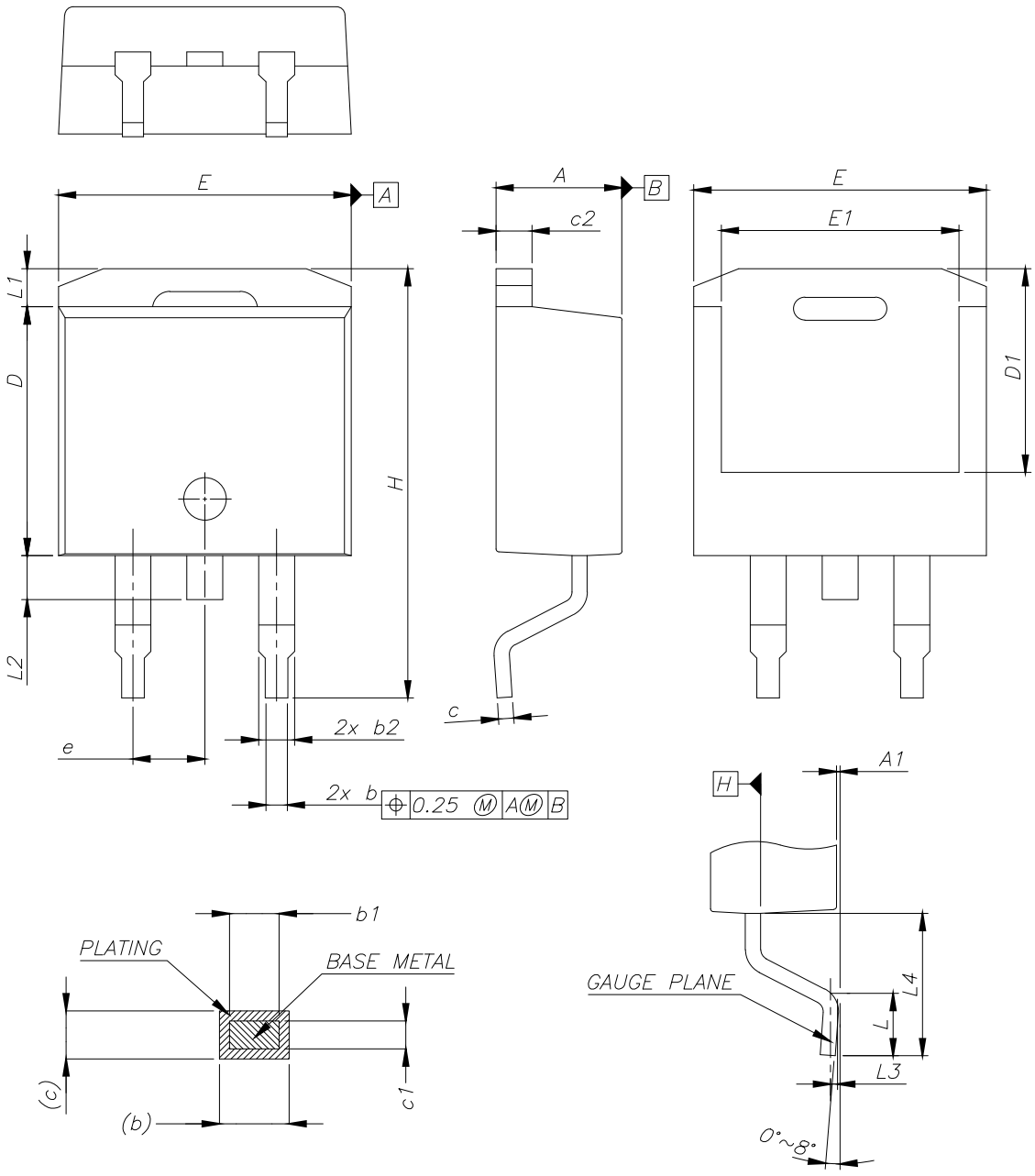
0079457_A2_27

Table 8. D²PAK (TO-263) type A2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.70	8.90	9.10
E2	7.30	7.50	7.70
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

4.2 D²PAK (TO-263) type B package information

Figure 20. D²PAK (TO-263) type B package outline

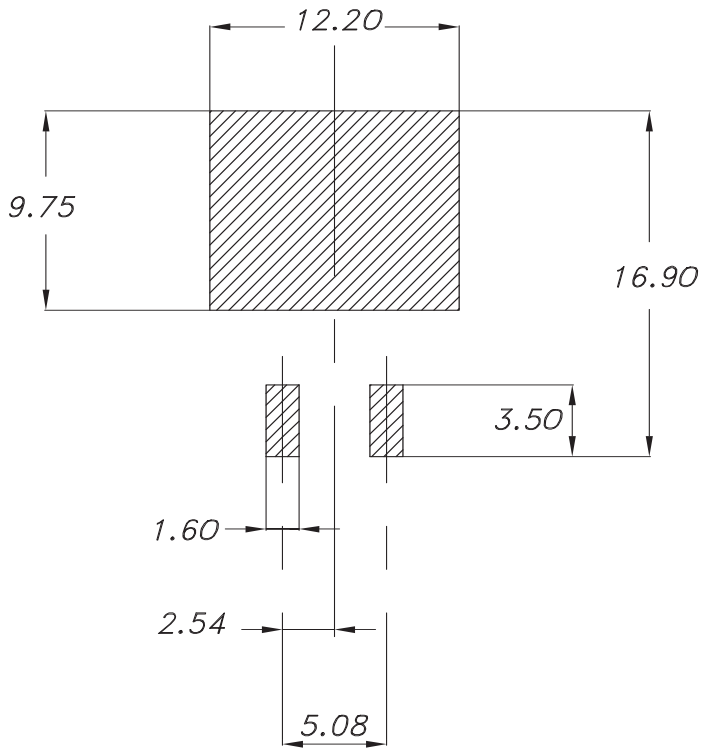


0079457_27_B

Table 9. D²PAK (TO-263) type B mechanical data

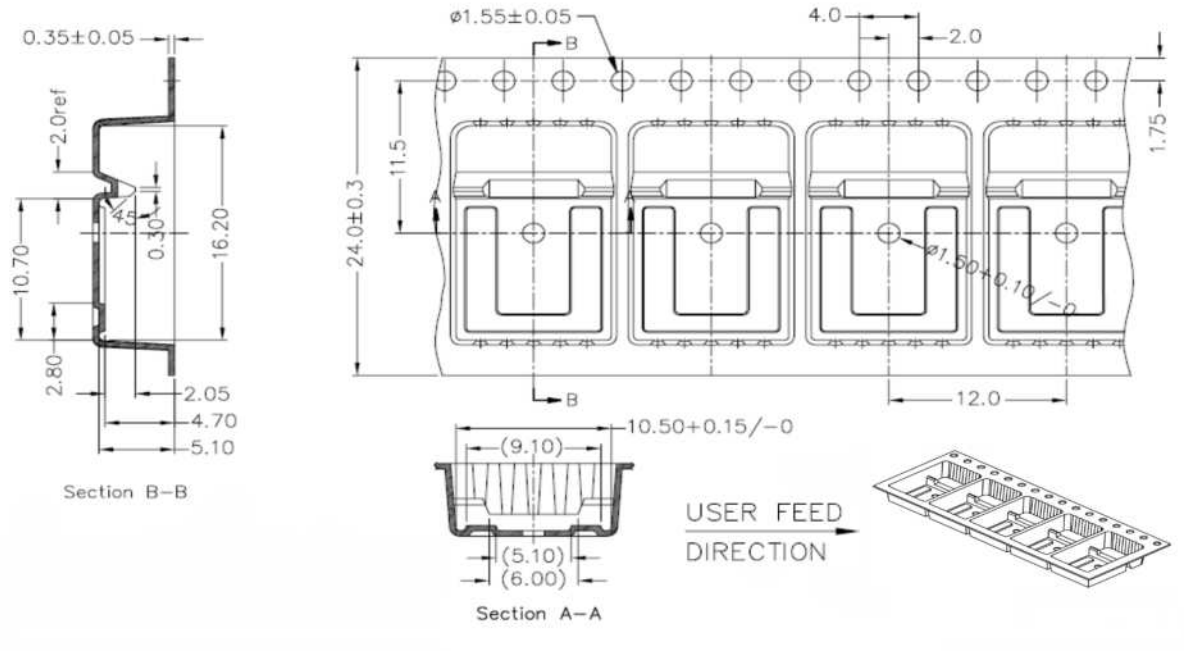
Dim.	mm		
	Min.	Typ.	Max.
A	4.36		4.56
A1	0.00		0.25
b	0.70		0.90
b1	0.51		0.89
b2	1.17		1.37
c	0.38		0.694
c1	0.38		0.534
c2	1.19		1.34
D	8.60		9.00
D1	6.90		7.50
E	10.15		10.55
E1	8.10		8.70
e	2.54 BSC		
H	15.00		15.60
L	1.90		2.50
L1			1.65
L2			1.78
L3		0.25	
L4	4.78		5.28

Figure 21. D²PAK (TO-263) recommended footprint (dimensions are in mm)



4.3 D²PAK packing information

Figure 22. **D²PAK tape drawing (dimensions are in mm)**



DM01095771_2

Revision history

Table 10. **Document revision history**

Date	Revision	Changes
14-Jun-2021	1	First release.
02-Sep-2025	2	Updated Section 4: Package information. Added Section 4.2: D²PAK (TO-263) type B package information.

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